

We claim:

1. A carrier and a chip configuration, comprising:

*Sub 30* a carrier having a metal area essentially composed of copper;

a chip having a rear side metallization layer;

a buffer layer configured on said metal area, said buffer layer being essentially composed of nickel and having a thickness between 5  $\mu\text{m}$  and 10  $\mu\text{m}$ ; and

a connecting medium for fixedly connecting said chip to said carrier;

said chip being configured, without a chip housing, on said metal area such that only said connecting medium is configured between said rear side metallization layer of said chip and said buffer layer.

2. The carrier and the chip configuration according to claim 1, wherein said buffer layer has a thickness between 7  $\mu\text{m}$  and 9  $\mu\text{m}$ .

3. The carrier and the chip configuration according to claim 2, wherein said rear side metallization layer is essentially composed of aluminum.

Sub B2  
4. The carrier and the chip configuration according to claim 1, wherein said rear side metallization layer is essentially composed of aluminum.

5. The carrier and the chip configuration according to claim 1, wherein said buffer layer has a surface facing said chip, and said surface facing said chip includes a protective layer that is essentially composed of gold.

6. The carrier and the chip configuration according to claim 1, wherein said carrier is essentially composed of copper.

Sub A2  
7. The carrier and the chip configuration according to claim 1, wherein said carrier includes a plate made of ceramic, said metal area is applied on said plate, and said chip has a contact area formed by said metal area.